

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t3512ems#trpbf

(Engineering Calculation)

MSOP with 4 PINS REMOVED

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TOTAL MASS (g) : 0.039077

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003694 | 1000000 | 94531.2421875 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013845 | 975000 | 354300.25 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000355 | 25000 | 9084.62109375 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 102.361938477 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 255.904830933 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.014214 | 1001000 | 363743.125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 18169.8828125 | | |
| | | External Plating Total: | | | | 0.000710 | 1000000 | 18169.8828125 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 2200.78149414 | | |
| Internal Plating Total: | | | | 0.000086 | 1000000 | 2200.78149414 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001075 | 750000 | 27509.7714844 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000358 | 250000 | 9161.39355469 | | |
| Die Attach Total: | | | | 0.001433 | 1000000 | 36671.1601562 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.002439 | 130000 | 62415.1914062 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.015571 | 830000 | 398469.4375 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000657 | 35000 | 16812.9492188 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000094 | 5000 | 2405.50561523 | | |
| | | Encapsulation Total: | | | | 0.018761 | 1000000 | 480103.0625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000179 | 1000000 | 4580.69677734 | | |
| | | | | | TOTAL MASS (g) : | 0.039077 | | |